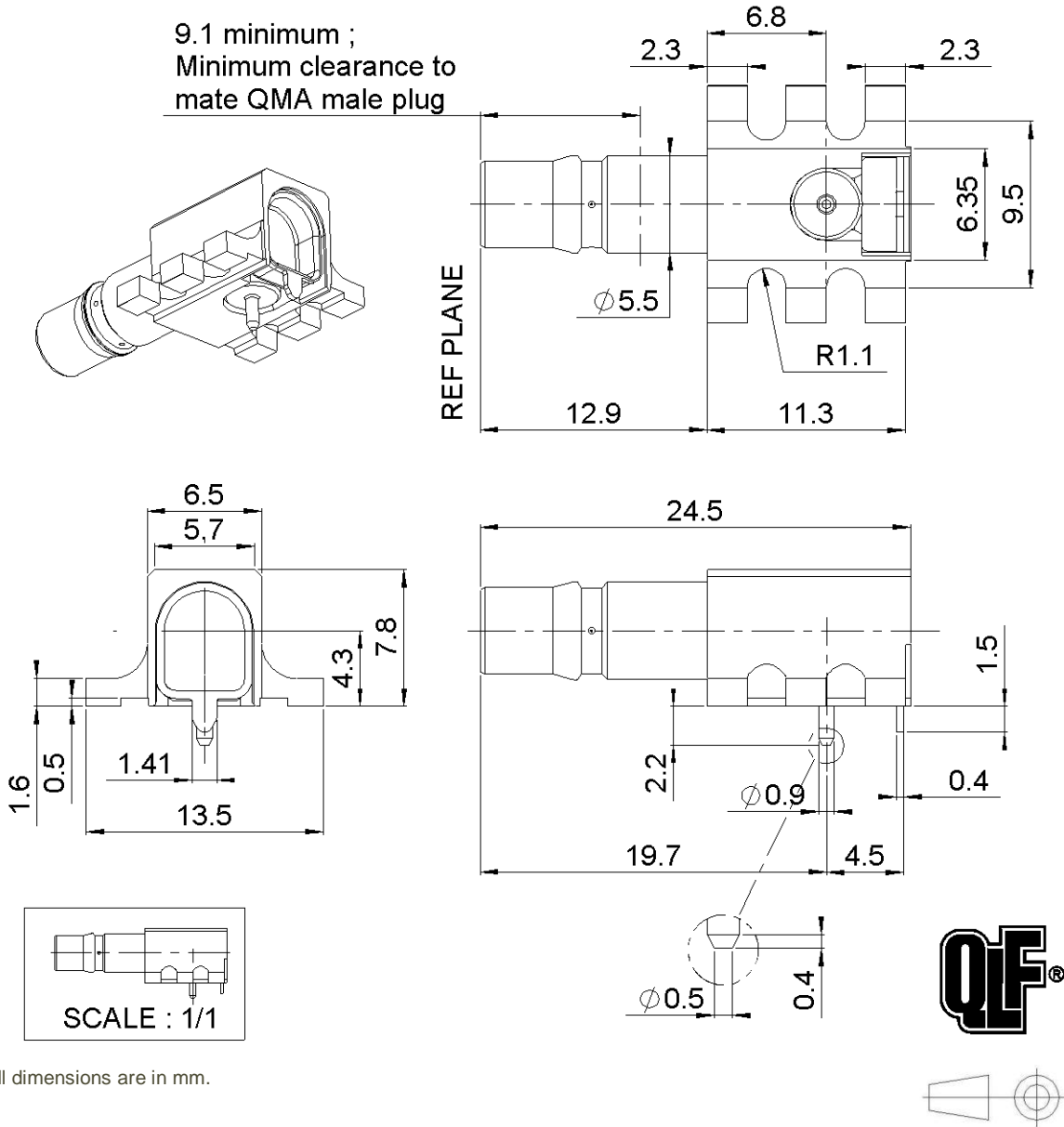


PAGE 1/5	ISSUE 02-06-16M	SERIES QMA	PART NUMBER R123682827
----------	-----------------	------------	------------------------



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
Body	BRASS	NPGR
Center contact	BERYLLIUM COPPER	NPGR
Outer contact	-	-
Insulator	PTFE	-
Gasket	-	-
Others parts	BRASS	NPGR
-	-	-
-	-	-

PAGE 2/5	ISSUE 02-06-16M	SERIES QMA	PART NUMBER R123682827
----------	------------------------	-------------------	-------------------------------

PACKAGING

Standard	Unit	Other
100	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance		50	Ω	
Frequency		0 - 6	GHz	
VSWR	1.05*	+	0.0000	x F(GHz) Maxi
Insertion loss			0.05	√F(GHz) dB Maxi
RF leakage	-	(80**	- F(GHz)) dB Maxi
Voltage rating			350	Veff Maxi
Dielectric withstanding voltage			1000	Veff mini
Insulation resistance			5000	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention				
Axial force – Mating End		27	N mini	
Axial force – Opposite end		27	N mini	
Torque		NA	N.cm mini	
Recommended torque				
Mating		NA	N.cm	
Panel nut		NA	N.cm	
Mating life		100	Cycles mini	
Weight		5.9500	g	

ENVIRONMENTAL

Operating temperature	-40/+105	°C	
Hermetic seal	NA	Atm.cm3/s	
Panel leakage	NA		

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:

***VSWR: up to 3GHz; 3-6GHz, 1.1 Max**

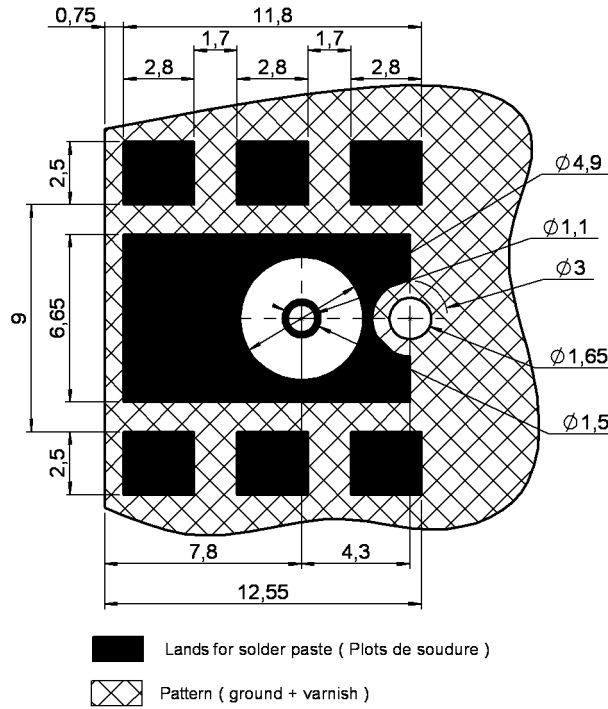
****RF leakage:Interf. only:3<F<6GHz:>70dB**

PAGE 3/5	ISSUE 02-06-16M	SERIES QMA	PART NUMBER R123682827
----------	-----------------	------------	------------------------

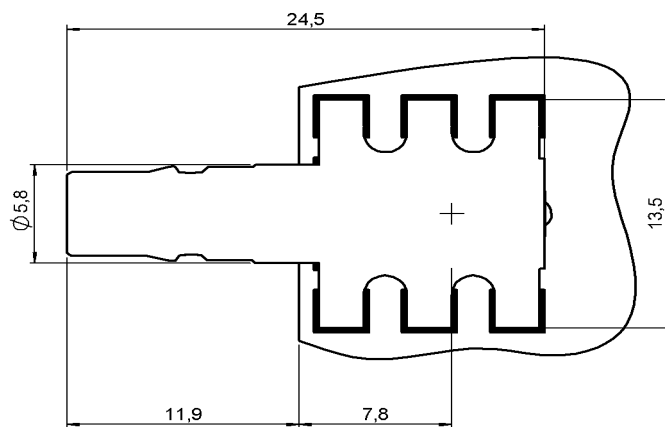
QMA SERIE - INFORMATIONS

Thickness of PCB = 0.063 (1.6mm).

The material of PCB is the epoxy resin of glass fabrics bacs (Er = 4.8). The solder resist should be printed except for the land pattern on the PCB.



SHADOW OF QUICLOCK RECEPTACLE FOR VIDEO CAMERA

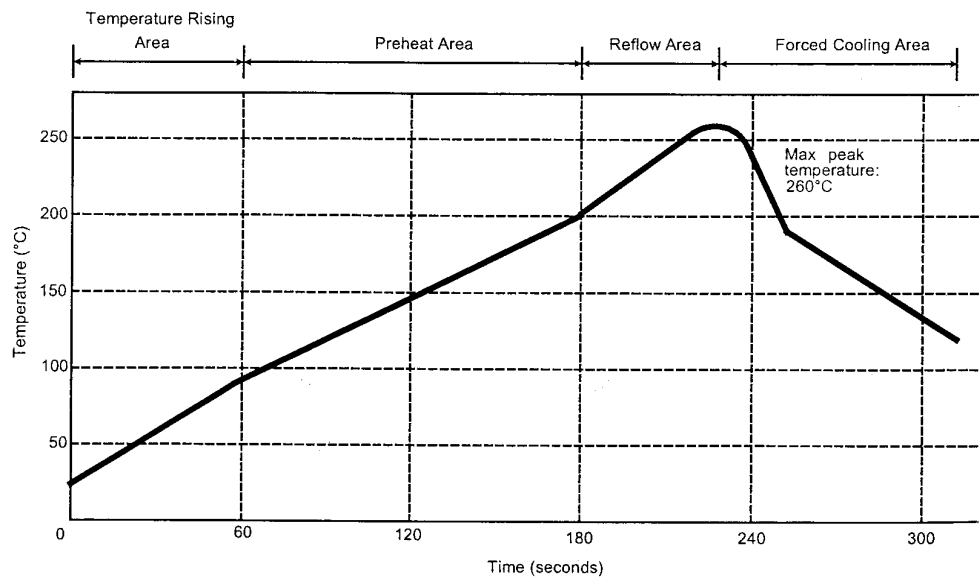


PAGE 4/5	ISSUE 02-06-16M	SERIES QMA	PART NUMBER R123682827
----------	------------------------	-------------------	-------------------------------

SOLDER PROCEDURE

1. Deposit solder paste 'Sn95 Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic 'pick and place' machine. Video camera is preferred to check the positioning of the component (See page 3). Adhesive agents are forbidden on the receptacle.
3. Soldering by infra-red reflow. We give under, the typical profile to use.
4. Cleaning of the printed circuits board.
5. Checking of solder joints and position of the components by visual inspection.

TEMPERATURE PROFIL



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec